

ABSTRACT OF THE DISCLOSURE

APPARATUS FOR REMOVING SEMICONDUCTOR WAFERS FROM WITHIN THE RUNNER DISKS OF A DOUBLE-SIDED POLISHING MACHINE

An apparatus for removing semiconductor wafers from within the runner disks in a double-sided polishing machine. The apparatus includes a suction head adapted to be connected to a vacuum, which has a plurality of suction ports such that all semiconductor wafers received by a runner disk may be gripped simultaneously. The apparatus also includes an arm on which the suction head is rotatably supported about a vertical axis and which, in turn, is pivotally supported about a vertical axis at a spacing from the suction head or is supported so as to be linearly adjustable or adjustable in height. The apparatus also includes a rotary drive for the suction head, a drive for the arm, a lifting drive for the arm, and a control device for activating the drives such that the semiconductor wafers may be deposited on a lay-down device in a predetermined, aligned position.